12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20251203002.1
Qualification of RFAB as an additional Fab site option, Die Revision and TI Philippines as additional Assembly site option for select devices
Change Notification / Sample Request

Date: December 04, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251203002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SN74LVC1G34DBVRE4	NULL
SN74LVC1G04DBVRE4	NULL
SN74LVC1G14DBVRG4	SN74LVC1G14DBVRG4

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251203002.1	PCN Date:	December 04, 2025
Title:	Qualification of RFAB as an additional Fab site option, Die Revision and TI Philippines as additional Assembly site option for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	March 04, 2026	Sample requests accepted until:	February 02, 2026*

*Sample requests received after February 02, 2026 will not be supported.

Change Type:

☒	Assembly Site	☒	Design	☐	Wafer Bump Material
☒	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option & TI Philippines as additional Assembly site option for devices in the product affected section.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
FFAB	ASLC10	200mm	RFAB	LBC9PLV	300mm

The die was also changed as a result of the process change.

Material differences as follows:

	Current site		Additional site
	ASEWH	**TFME**	**TI Philippines**
Wire bond diam/type	1.0mil Au	1.0mil Au	0.8mil Cu
Mount compound	SID#1120999A2	SID# A-03	8095733
Mold compound	SID#4020039A1	SID#R-13	4222198

Marking differences are as follows:

Device name	Current Symbol	Additional Symbol
SN74LVC1G34DBVRG4 SN74LVC1G34DBVRE4	C345, C34S	41LF
SN74LVC1G17DBVRG4 SN74LVC1G17DBVRE4	C17F	41MF
SN74LVC1G14DBVRG4 SN74LVC1G14DBVRE4	C14F	41NF
SN74LVC1G07DBVRG4 SN74LVC1G07DBVRE4	C07F	41OF
SN74LVC1G06DBVRG4 SN74LVC1G06DBVRE4	C06F	41PF
SN74LVC1G04DBVRG4 SN74LVC1G04DBVRE4	C04, C04P	3VIF

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FFAB	TID	DEU	Freising
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
A, D, G	**A**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
ASEWH	AWH	CHN	Weihai
TFME	NFM	CHN	Chongchuan
TI Philippines	**PHI**	**PHL**	**Baguio City**

Sample product shipping label (not actual product label):

Product Affected:

SN74LVC1G04DBVRG4	SN74LVC1G07DBVRG4	SN74LVC1G17DBVRG4
SN74LVC1G04DBVRE4	SN74LVC1G07DBVRE4	SN74LVC1G17DBVRE4
SN74LVC1G06DBVRG4	SN74LVC1G14DBVRG4	SN74LVC1G34DBVRG4
SN74LVC1G06DBVRE4	SN74LVC1G14DBVRE4	SN74LVC1G34DBVRE4

Qualification Report

Approve Date 25-SEPTEMBER-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74LVC1G04DBVRG4	Qual Device: SN74LVC1G06DBVRG4	QBS Reference: TLV1805QDBVRQ1	QBS Reference: SN74HCS74QPWRQ1	QBS Reference: TLV9061SQDBVRQ1	QBS Reference: TLV1805QDBVRQ1	QBS Reference: SN74LVC1G16DBVR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	3/231/0	3/231/0	3/231/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	3/135/0	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	3/231/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	-	-	1/77/0
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	1/15/0	1/15/0	1/15/0	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	3/30/0	3/30/0	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	250 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	500 Volts	-	-	1/3/0	1/3/0	-	-	-
ESD	E2	ESD HBM	-	1000 Volts	1/3/0	1/3/0	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	1/3/0	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	1/6/0	1/6/0	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	-	-	-	-	1/30/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	3/90/0	3/90/0	3/90/0	3/90/0	-

QBS: Qual By Similarity, also known as Generic Data
Qual Device SN74LVC1G04DBVRG4 is qualified at MSL1 260C
Qual Device SN74LVC1G06DBVRG4 is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2505-001

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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